ESD Protection Diodes

Ultra Low Capacitance ESD Protection Diode for High Speed Data Line

The ESD81x1 Series ESD protection diodes are designed to protect high speed data lines from ESD. Ultra-low capacitance and low ESD clamping voltage make this device an ideal solution for protecting voltage sensitive high speed data lines.

Features

- Low Capacitance (0.20 pF Typ, I/O to GND)
- Protection for the Following IEC Standards: IEC 61000–4–2 (Level 4)
- Low ESD Clamping Voltage
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

Typical Applications

- USB 3.0/3.1
- MHL 2.0
- eSATA

MAXIMUM RATINGS (T_J = 25°C unless otherwise noted)

Rating	Symbol	Value	Unit
Operating Junction Temperature Range	T_J	-55 to +150	°C
Storage Temperature Range	T _{stg}	-55 to +150	°C
Lead Solder Temperature – Maximum (10 Seconds)	T _L	260	°C
ESD8101: IEC 61000-4-2 Contact IEC 61000-4-2 Air ESD8111: IEC 61000-4-2 Contact IEC 61000-4-2 Air	ESD	±23 ±23 ±30 ±30	kV kV kV

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

See Application Note AND8308/D for further description of survivability specs.

This document contains information on some products that are still under development. ON Semiconductor reserves the right to change or discontinue these products without notice.



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MARKING DIAGRAMS



ESD8101 (01005) DSN2 CASE 152AK





ESD8101P (01005) DSN2 CASE TBD*





ESD8111 (0201) WLCSP2 CASE 567AV





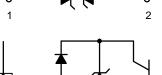
ESD8111P (0201) WLCSP2 CASE TBD*



T, F, X = Device Code M = Date Code

* In Development

PIN CONFIGURATION AND SCHEMATIC



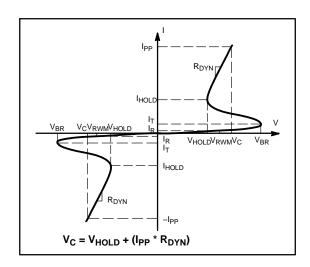
ORDERING INFORMATION

See detailed ordering and shipping information on page 2 of this data sheet.

ELECTRICAL CHARACTERISTICS

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$

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Symbol	Parameter	
V _{RWM}	Working Peak Voltage	
I _R	Maximum Reverse Leakage Current @ V _{RWM}	
V _{BR}	Breakdown Voltage @ I _T	
Ι _Τ	Test Current	
V _{HOLD}	Holding Reverse Voltage	
I _{HOLD}	Holding Reverse Current	
R _{DYN}	Dynamic Resistance	
I _{PP}	Maximum Peak Pulse Current	
V _C	Clamping Voltage @ I _{PP} V _C = V _{HOLD} + (I _{PP} * R _{DYN})	



ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise specified)

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Reverse Working Voltage	V_{RWM}	I/O Pin to GND			3.3	V
Breakdown Voltage	V_{BR}	I _T = 1 mA, I/O Pin to GND	5.5	7.9	8.6	V
Reverse Leakage Current	I _R	V _{RWM} = 3.3 V, I/O Pin to GND			1.0	μΑ
Reverse Holding Voltage	V _{HOLD}	I/O Pin to GND		2.1		V
Holding Reverse Current	I _{HOLD}	I/O Pin to GND		17		mA
ESD8101, ESD8111 Clamping Voltage TLP (Note 1)	V _C	I _{PP} = 8 A		6.5		V
		(±8 kV Contact, ±15 kV Air)				
Junction Capacitance	CJ	$V_R = 0 \text{ V}, f = 1 \text{ MHz}$		0.2	0.4	pF

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

ORDERING INFORMATION

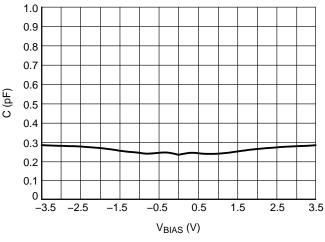
Device	Package	Shipping [†]
ESD8101FCT5G	DSN2 (Pb-Free)	10,000 / Tape & Reel
ESD8111FCT5G	WLCSP2 (Pb-Free)	10,000 / Tape & Reel
ESD8101PFCT5G**	Side wall Isolated 01005	10,000 / Tape & Reel
ESD8111PFCT5G**	Side wall Isolated 0201	10,000 / Tape & Reel

^{**} In Development. Contact local sales rep for availability.

^{1.} ANSI/ESD STM5.5.1 – Electrostatic Discharge Sensitivity Testing using Transmission Line Pulse (TLP) Model. TLP conditions: $Z_0 = 50 \ \Omega$, $t_p = 100 \ ns$, $t_r = 4 \ ns$, averaging window; $t_1 = 30 \ ns$ to $t_2 = 60 \ ns$.

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

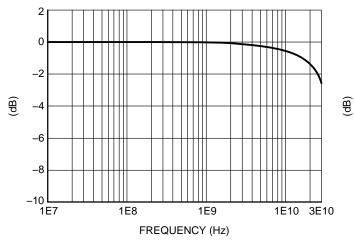
TYPICAL CHARACTERISTICS



1.0 0.9 0.8 0.7 0.6 C (pF) 0.5 0.4 0.3 0.2 0.1 -0.5 0.5 1.5 -3.5 -2.5 -1.5 2.5 3.5 V_{BIAS} (V)

Figure 1. ESD8101 CV Characteristics

Figure 2. ESD8111 CV Characteristics



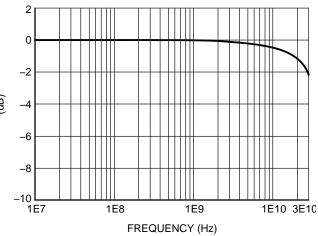
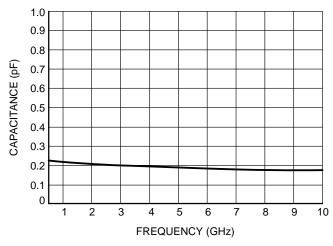


Figure 3. ESD8101 S21 Insertion Loss

Figure 4. ESD8111 S21 Insertion Loss



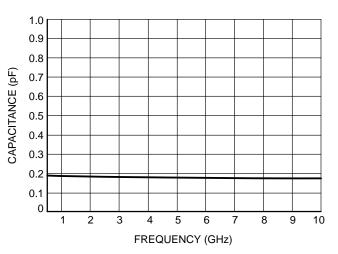


Figure 5. ESD8101 Capacitance over Frequency

Figure 6. ESD8111 Capacitance over Frequency

TYPICAL CHARACTERISTICS

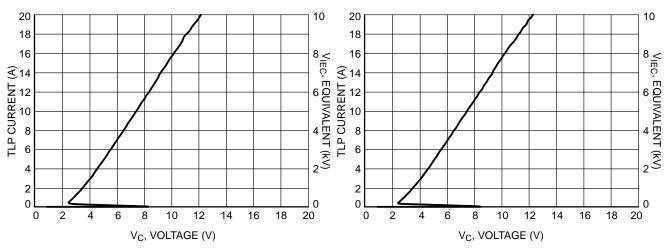


Figure 7. ESD8101 Positive TLP I-V Curve

Figure 8. ESD8111 Positive TLP I-V Curve

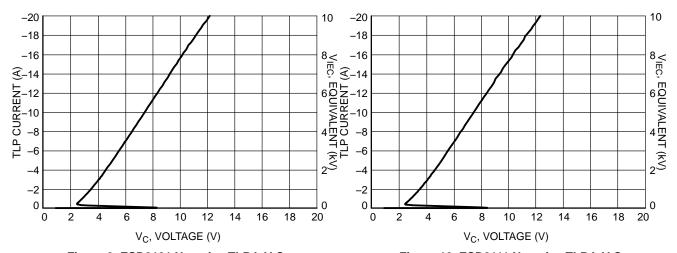


Figure 9. ESD8101 Negative TLP I-V Curve

Figure 10. ESD8111 Negative TLP I-V Curve

IEC 61000-4-2 Spec.

	•			
Level	Test Volt- age (kV)	First Peak Current (A)	Current at 30 ns (A)	Current at 60 ns (A)
1	2	7.5	4	2
2	4	15	8	4
3	6	22.5	12	6
4	8	30	16	8

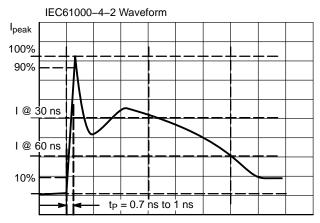


Figure 11. IEC61000-4-2 Spec

Transmission Line Pulse (TLP) Measurement

Transmission Line Pulse (TLP) provides current versus voltage (I–V) curves in which each data point is obtained from a 100 ns long rectangular pulse from a charged transmission line. A simplified schematic of a typical TLP system is shown in Figure 12. TLP I–V curves of ESD protection devices accurately demonstrate the product's ESD capability because the 10s of amps current levels and under 100 ns time scale match those of an ESD event. This is illustrated in Figure 13 where an 8 kV IEC 61000–4–2 current waveform is compared with TLP current pulses at 8 A and 16 A. A TLP I–V curve shows the voltage at which the device turns on as well as how well the device clamps voltage over a range of current levels.

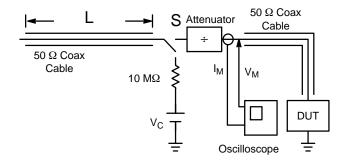


Figure 12. Simplified Schematic of a Typical TLP System

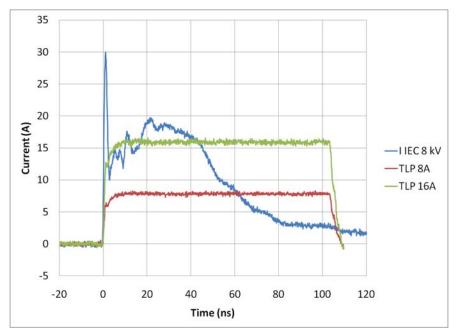
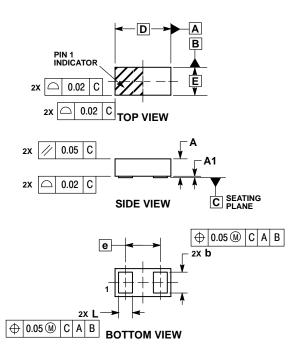


Figure 13. Comparison Between 8 kV IEC 61000-4-2 and 8 A and 16 A TLP Waveforms

PACKAGE DIMENSIONS - ESD8101 (01005)

DSN2, 0.435x0.23, 0.27P, (01005) CASE 152AK **ISSUE A**

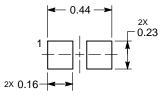


NOTES:

- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 CONTROLLING DIMENSION: MILLIMETERS.

	MILLIMETERS		
DIM	MIN	MAX	
Α	0.165	0.195	
A1		0.030	
b	0.177	0.193	
D	0.435 BSC		
Е	0.230 BSC		
е	0.270 BSC		
1	0 112	0 128	

RECOMMENDED SOLDER FOOTPRINT*



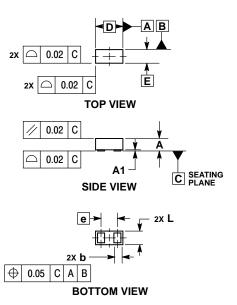
DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS - ESD8111 (0201)

WLCSP2, 0.6x0.3 CASE 567AV

ISSUE A

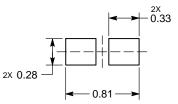


NOTES:

- 1. DIMENSIONING AND TOLERANCING PER
- ASME Y14.5M, 1994. CONTROLLING DIMENSION: MILLIMETERS.

_	MILLIMETERS		
DIM	MIN	MAX	
Α	0.25	0.30	
A1	0.00	0.05	
b	0.14	0.17	
D	0.60 BSC		
Е	0.30 BSC		
е	0.36 BSC		
	0.19	0.24	

RECOMMENDED SOLDER FOOTPRINT*

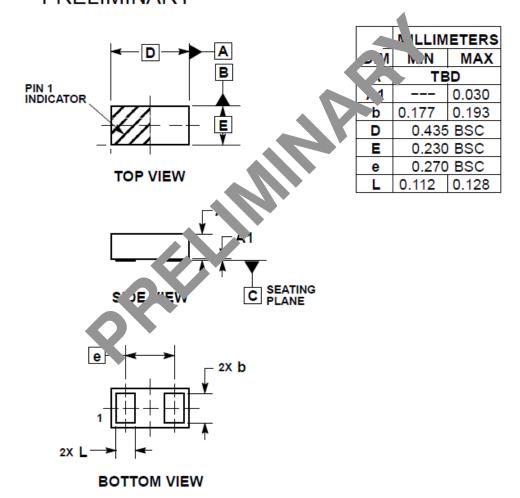


DIMENSIONS: MILLIMETERS

^{*}For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

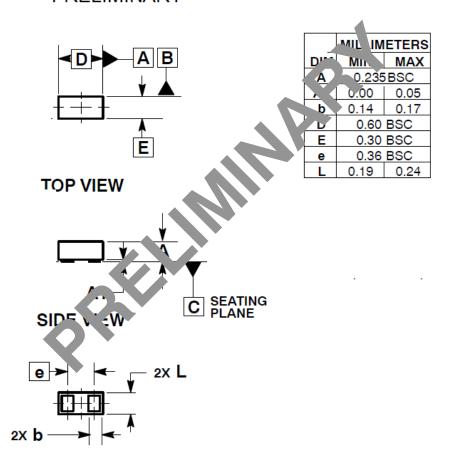
PACKAGE DIMENSIONS - ESD8101P (01005)

Side Wall Isolated 0.435x0.23 [01005] CASE TBD PRELIMINARY



PACKAGE DIMENSIONS - ESD8111P (0201)

Side Wall Isolated 0.6x0.3 [0201] CASE TBD PRELIMINARY



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